L	Hits	Search Text	DB	Time stamp
Number			ŀ	_
1	0	semiconductor near10 packag\$3 and chip	USPAT;	2004/09/23
		and metal adj plates and plugs and pads	EPO; JPO; DERWENT	11:56
2	3	semiconductor near10 packag\$3 and chip	USPAT;	2004/09/23
		and metal near5 plates and plugs and pads	EPO; JPO; DERWENT	11:59
3	32	· · · · · · · · · · · · · · · · · · ·	USPAT;	2004/09/23
		and plates and plugs and pads	EPO; JPO; DERWENT	11:59
4	29	(semiconductor near10 packag\$3 and chip	USPAT;	2004/09/23
		and plates and plugs and pads) not	EPO; JPO;	11:59
		(semiconductor near10 packag\$3 and chip and metal near5 plates and plugs and	DERWENT	
		pads)		